

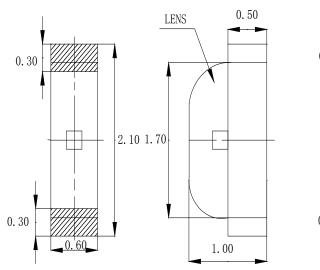
#### **Features**

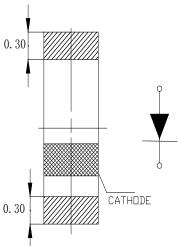
- · 2.1mm\*1.0mm SMT LED, Super thin (0.60H mm)
- · Low Power Consumption
- · Wide Viewing Angle
- · Various Colors
- · Compatible with automatic placement equipment.
- · Compatible with infrared and vapor phase reflow and wave solder process.
- · Meet ROHS Green Product
- · Package: 3000pcs/Reel

## **Applications**

· Backlight and Indicator

# **Package Dimensions**





#### **Notes:**

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.2$ mm(.0079") unless otherwise noted.
- 3. Specifications are subject to change without notice
- 4. This drawing is only for reference, not as a basis for the actual structure.

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S	Selection Guide							
	Part No	Lens Type	Dice	Emitted Color				
	FSL-2110060G- SNCZYH	Water Clear	InGaN	Green				

# Electrical / Optical Characteristics At Ta=25 °C

Symbol	Parameter		Тур.	Max.	Unit	Test Condition
Iv	Luminous Intensity		9.0	11.5	mcd	IF=5mA
201/2	Viewing Angle		130		deg	IF=5mA
入 Peak	入 Peak		570		nm	IF=5mA
λd	d Dominant Wavelength		571.0	575.5	nm	IF=5mA
Δλ	Spectral Line Half-Width		15		nm	IF=5mA
VF	VF Forward Voltage		2.0	2.35	V	IF=5mA
IR	Reverse Current			10	uA	VR 5V

Note:

### Absolute Maximum Ratings At Ta=25℃

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Parameter	Green	Unit	
Power Dissipation	75	mW	
Peak Forward Current[1]	80	mA	
Continuous Forward Current	30	mA	
Dreading Linear From50°C	0.4	mA/℃	
Reverse Voltage	5	V	
Electrostatic Discharge Threshold(HBM)	2000	V	
Operating Temperature Range	-55°C to + 85°C		
Storage Temperature Range	-55°C to + 85°C		
Soldering Condition	260°C For5 Seconds		

Note

1. 1/10DutyCycle,0.1msPulseWidth

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 $<sup>1. \</sup>theta 1/2$  is the angle from optical centerline where the luminous intensity is 1/2 optical centerline value



### Electrical Optical Characteristics Curves At Ta=25 °C

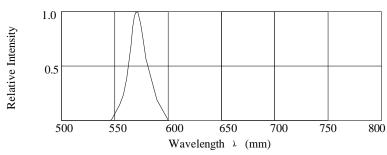
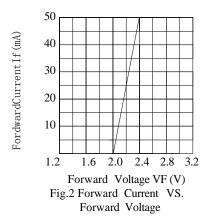
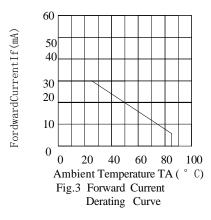
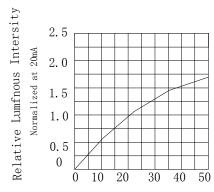


Fig.1 Rekative Intensity vs. Wavekength







Forward Current (mA)
Fig.4 Relative Luminous
Intensity vs. Forward Current

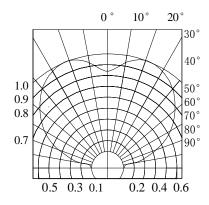


Fig.6 Spatial Distribution

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## **Bin Range Of Luminous Intensity**

Symbol	Bin Code	Min.	Max.	Unit	Condition
	J1	4.5	5.8	med IF:	
T	J2	5.8	7.2		IF=5mA
Iv	K1	7.2	9.0		
	K2	9.0	11.5		

## **Bin Range Of Forward Voltage**

Symbol	Bin Code	Min.	Max.	Unit	Condition
	V2	1.75	1.95		
VF	V3	1.95	2.15	V	IF=5mA
	V4	2.15	2.35		

# **Bin Range Of Dominate Wavelength**

Symbol	Bin Code	Min.	Max.	Unit	Condition
	DB	567.5	569.5	nm	IF=5mA
λ .1	DC	569.5	571.5		
λd	DD	571.5	573.5		
	DE	573.5	575.5		

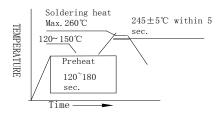
#### Notes:

- 1. Tolerance of Luminous Intensity +/-20%
- 2. Tolerance of Forward Voltage +/-0.15V
- 3. Tolerance of the Dominate Wavelength +/- 2nm

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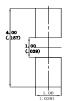
#### **SMT Reflow Soldering Instructions**



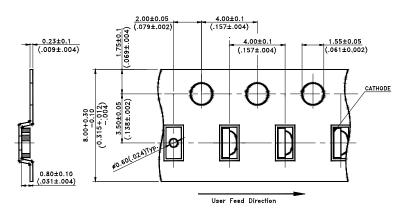
#### Notes:

- Seller gives no other assurances regarding the ability of to withstand ESD. It is recommended to use a
  wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must
  be properly grounded.
- 2. Reflow soldering should not be done more than two times.
- 3. Do not stress LED when soldering, and do not warp the circuit board after soldering
- 4. While using Iron, Power dissipation of Iron should be smaller than 25W, and temperature should be controllable. The work should be finished within 2 sec under 320°C for once only.

#### **Recommended Soldering Pad Dimensions**



#### Package Specifications (Units: mm(inches))



#### Notes:

- 1. The LEDs should be used within a year.
- 2. The LEDs should be kept in  $5\sim30^{\circ}\text{C}$  and 60% RH for less.
- 3. The LEDs should be used within 24 hours, or else should be kept a 5~30°C and 30% RH or less. And LEDs should be used within 7 days after opening the package.

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# **Reliability Test Items Conditions**

Classification	Test Item	Test Conditions	Test hours	Result
	Opertion Life	Connect with a power IF=5mA Ta=Under room temperature	1000Hrs	0/20
F 1	Hige Temperature High Humidity	Ta=+65°C±5°C RH=90%-95%	240Hrs	0/20
Endurance Test	Hige Temperature Storage	High Ta=+85°C±5°C	1000Hrs	0/20
	Low Temperature Storage	Low Ta=-35°C±5°C Test time=1000hrs	1000Hrs	0/20
	Temperature Cycling	-45°C∼+105°C 15min 5min 15min	300 Cycles	0/20
Environmental	Thermal Shock	-35°C ~±5°C ~+85°C ~±5°C 5min 10sec 5min	300 Cycles	0/20
Test	Solder Resistance	Preheating: 120°C-150°C, within 2 minutes. Operation heating: 260°C (Max.), within 5 seconds (Max.)	5Cycles	0/20

# Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V <sub>F</sub> (V)	IF=5mA	Over U×1.2
Rvevrse current	Ir(µA)	V <sub>R</sub> =5V	Over U×2
Luminous intensity	Iv(mcd)	IF=5mA	Below S×0.5

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Meansurment shall be taken between 2 hours after the test pieces have been returned to normal ambient conditions after completion of each test.

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